

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

#### Notification# 20201014001 Datasheet for TMP175, TMP75 Information Only

Date: January 12, 2021 To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team (<u>PCN ww admin team@list.ti.com</u>).

Sincerely,

Change Management Team SC Business Services

### Information Only Attachments

## **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

# DEVICE

TMP75AIDGKT

CUSTOMER PART NUMBER null

Technical details of this Product Change follow on the next page(s).

Title: Datasheet	for TMP175, TMP75							
Customer Contact:		De	ept:	Quality Services				
Change Type: Elect								
Description of Cha	nge:							
	ncorporated is announcing	g an information only no	otifica	tion.				
-	et(s) is being updated as							
The following change	e history provides further	details.						
TEXAS INSTRUMENTS		0000000		TMP175, TMP				
	•	SD03200W	I – JANUA	ARY 2004 – REVISED OCTOBER 2				
	ion L (December 2015) to Rev			Page				
	ering format for tables, figures,							
-	maximum Supply voltage of T							
	pins to Input voltage specification							
	e maximum Input Voltage of TM e maximum of TMP75 A2 pin vo							
Changed Absolute maximum of TMP75 A2 pin voltage from 7 V to (V+)+0.3								
Updated TMP75 D and DGK package Thermal Information								
	D package Thermal Information							
<ul> <li>Added register set</li> </ul>	tings to Conversion time specifi	cation for clarity		6				
-	n Data setup specification time f							
-		-	Moved Timeout specification to I2C Interface Timing table					
-	Timeout specification minimum	fram DE to DO		_				
	Timeout specification maximum	from 74 to 30		7				
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TMP175AIDR		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
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